



CSP Program Summit 2016

# Robust, Cost-Effective Heat Exchangers for 800°C Operation with Supercritical CO<sub>2</sub>

[energy.gov/sunshot](http://energy.gov/sunshot)

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Ken H. Sandhage, Reilly Professor, School of Materials  
Engineering, Purdue University, W. Lafayette, IN

# The Team

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## Principal Investigators:

**Ken H. Sandhage**

*School of Materials Engineering  
Purdue University, W. Lafayette, IN*

**Devesh Ranjan, Asegun Henry**

*School of Mechanical Engineering  
Georgia Institute of Technology, Atlanta, GA*

**Mark H. Anderson**

*Department of Engineering Physics  
University of Wisconsin, Madison, WI*



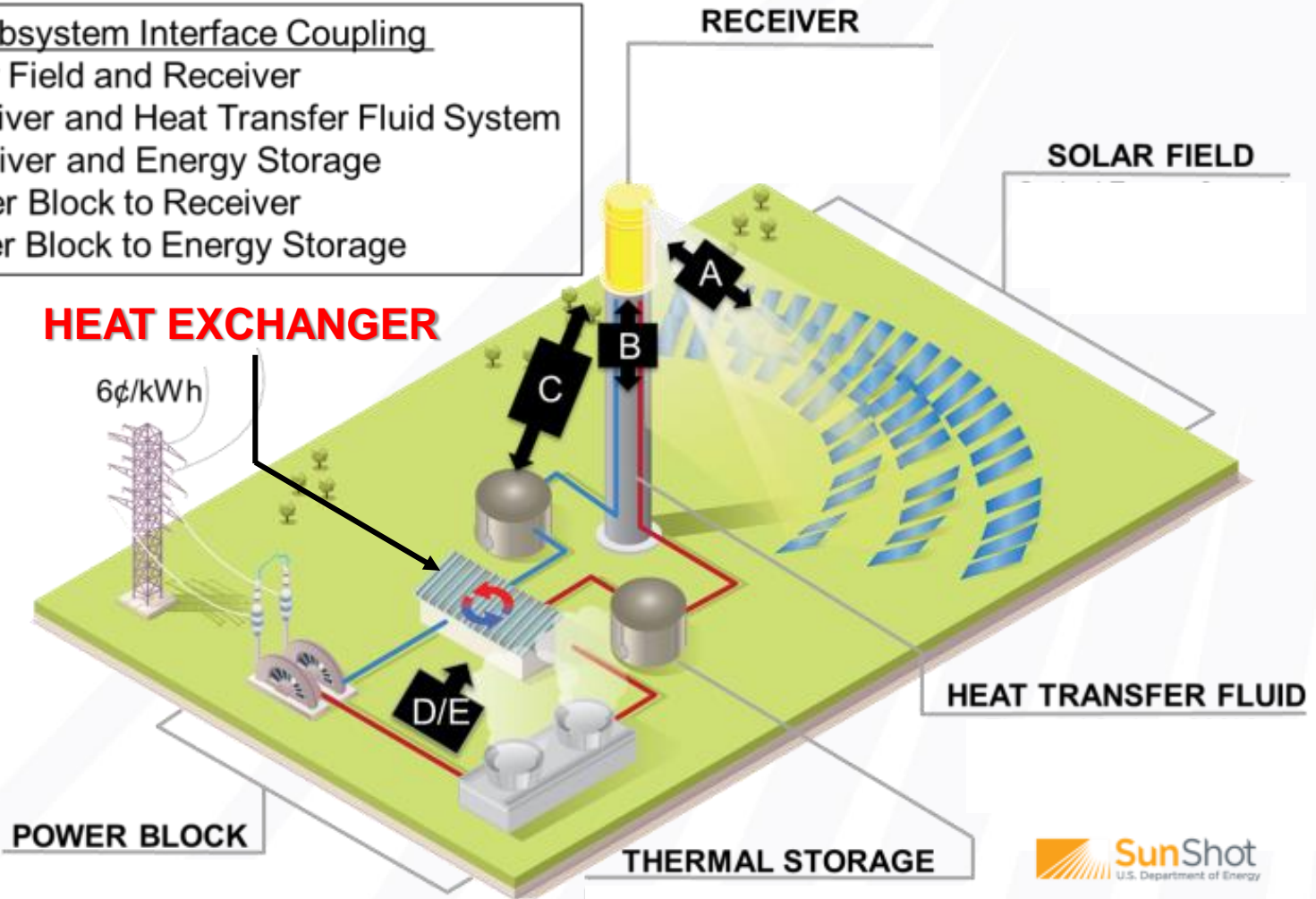
## Areas of Expertise:

- Ceramics processing
- Net-shape/net-size manufacturing
- Simulation and testing of thermal behavior
- High-temperature, high-pressure fluid dynamics
- High-temperature, high-pressure corrosion
- Design of high-temperature supercritical systems

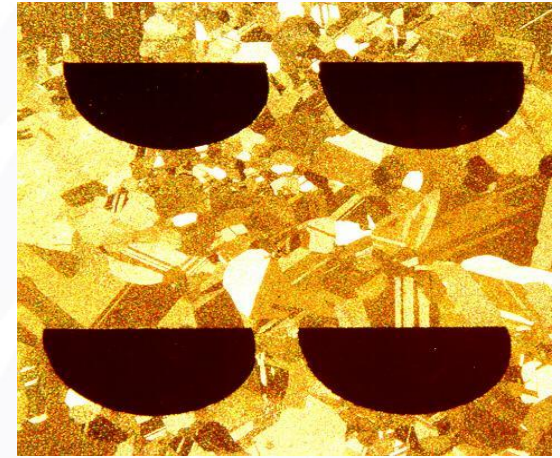
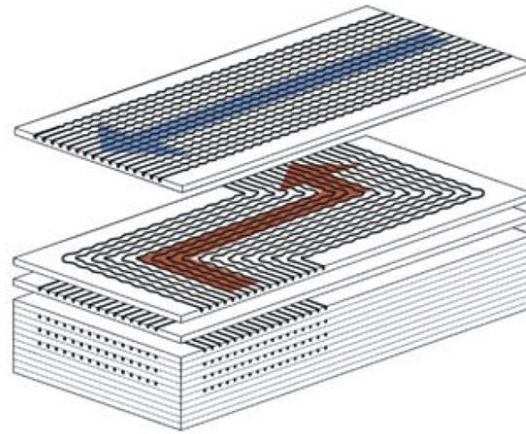
# Technology Focus

## CSP Subsystem Interface Coupling

- A: Solar Field and Receiver
- B: Receiver and Heat Transfer Fluid System
- C: Receiver and Energy Storage
- D: Power Block to Receiver
- E: Power Block to Energy Storage



# State of the Art: Metallic Alloy Printed Circuit HEXs



## Current Technology:

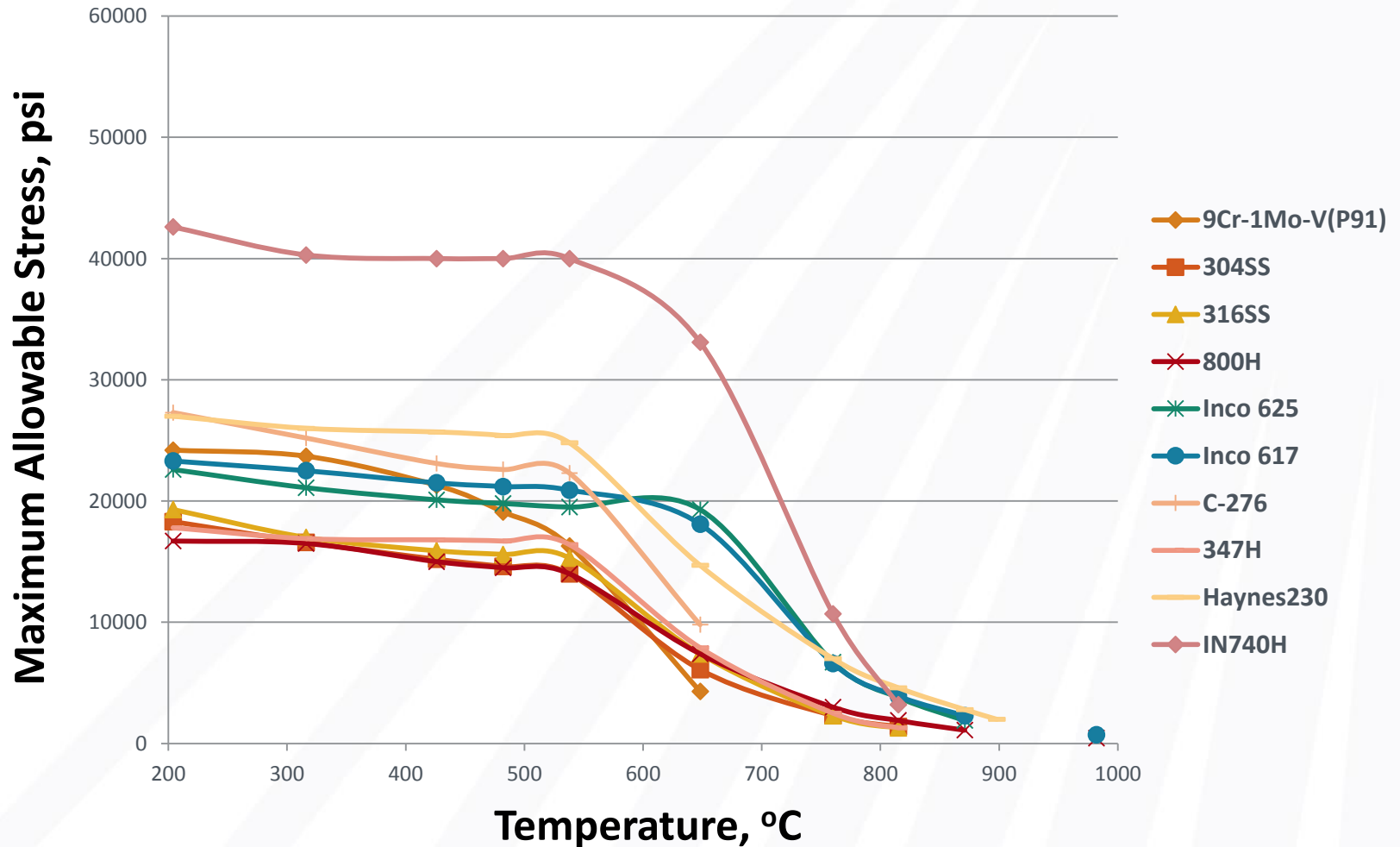
- Printed Circuit HEXs: patterned etching of metallic alloy plates, then diffusion bonding
- Upper use temperature of conventional alloys < 600°C





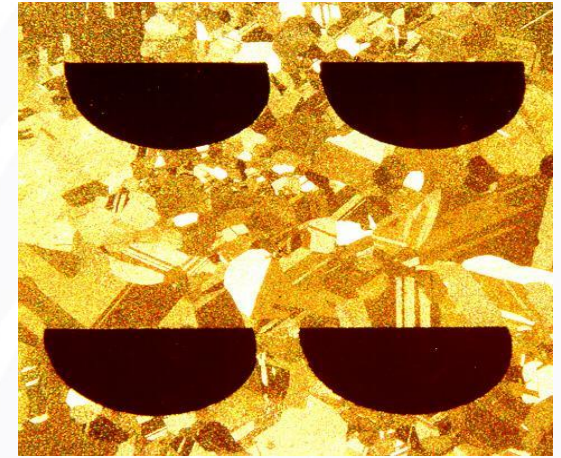
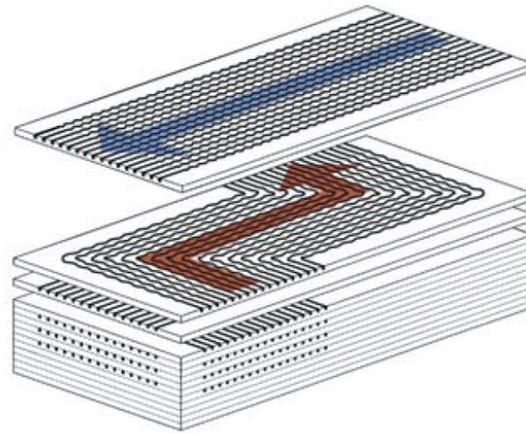
# State of the Art: Metallic Alloy Printed Circuit HEXs

## Allowable Material Stress vs. Temperature



2010 ASME Boiler Pressure Vessel Code, Sec. II, from Tables 1A and 1B, July 1, 2010, New York, NY (compiled by Mark Anderson)

# State of the Art: Metallic Alloy Printed Circuit HEXs



## Current Technology:

- Printed Circuit HEXs: patterned etching of metallic alloy plates, then diffusion bonding
- Upper use temperature of conventional alloys  $< 600^{\circ}\text{C}$

## New Technology:

- Toughened ceramic-based HEXs: preform pressed into HEX shape, then converted into toughened composite
- Higher temperature, higher stiffness, thermally-conductive material for use at  $\geq 800^{\circ}\text{C}$



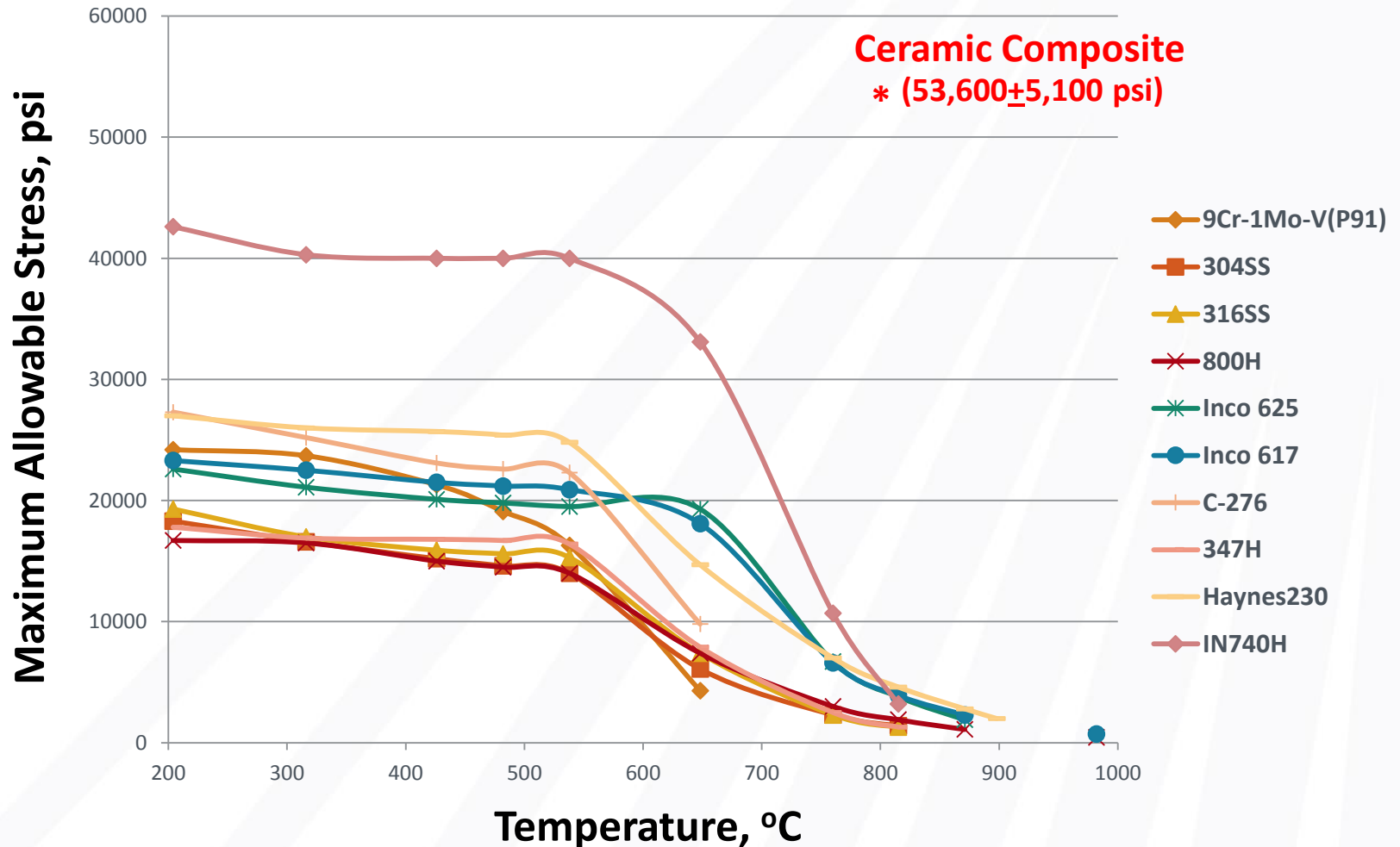
# Attractive Characteristics of Our Toughened Ceramic Composite Material

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- ◆ **High melting point** ( $T_m > 1,600^\circ\text{C}$ ; higher than conventional stainless steels or Ni-based structural alloys)
- ◆ **Retention of stiffness and strength at  $800^\circ\text{C}$**  ( $E \geq 28 \times 10^6$  psi/ $193$  GPa;  $\sigma_f \geq 50 \times 10^3$  psi/ $350$  MPa at RT and at  $800^\circ\text{C}$ )

# State of the Art: Metallic Alloy Printed Circuit HEXs

## Allowable Material Stress vs. Temperature



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- ◆ **Enhanced toughness w.r.t. conventional monolithic ceramics** ( $K_{1c} = 8 \pm 2$  MPa·m<sup>1/2</sup> vs.  $\leq 0.8$  MPa·m<sup>1/2</sup> for Pyrex glass,  $\leq 1.4$  MPa·m<sup>1/2</sup> for concrete, and  $\leq 4.6$  MPa·m<sup>1/2</sup> for Hexoloy SiC)
- ◆ **High thermal conductivity** ( $\kappa = 65.8$  W/m·K at  $800^\circ\text{C}$  vs. 22.1 W/m·K for IN740H alloy, and 24.4 W/m·K for H230 alloy)
- ◆ **Chemical stability** (Thermodynamic calculations indicate resistance to chloride fluids at  $800^\circ\text{C}$ ; Chemical tailoring underway for resistance to SC-CO<sub>2</sub> fluids at 750- $800^\circ\text{C}$  and 20 MPa)
- ◆ **Low-cost pressing + net-shape/size reaction process** ( $\Delta L/L_0 < 1\%$ )

# Net-Shape, Net-Size Ceramic Composites

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- ◆ **Green body (“preform”) plates with desired channel patterns are first generated by low-cost forming (e.g., pressing with stamped channel patterns).**

# Low-Cost Fabrication of Plate-Shaped Preforms

Preform

Channeled Preform

Fabricate pairs of plate-shaped preforms, with one of the plates containing patterned milli-channels, via uniaxial pressing



Top-down view of an airfoil millichannel pattern



Top-down view of a zig-zag millichannel pattern

# Net-Shape, Net-Size Ceramic Composites

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- ◆ Green body (“preform”) plates with desired channel patterns are first generated by low-cost forming (e.g., pressing with stamped channel patterns).
- ◆ The preform is then converted into the final desired high-temperature ceramic composite material via a *shape-preserving* reaction process.
- ◆ The dimensional changes before and after such reaction are well below 1%. => This is also a *size-preserving* process.



# Shape- and Size-Preserving Reaction Process

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Preform

Fabricate pairs of plate-shaped preforms, with one of the plates containing patterned milli-channels, via uniaxial pressing

Channeled Preform

↓ **Reactive Conversion**

Ceramic Composite

Generate net-shape, net-size toughened ceramic composite plates via reaction process

Channeled Ceramic Composite

# Joining of Heat Exchanger Components

Preform

Channeled Preform

↓ Reactive Conversion

Ceramic Composite

Channeled Ceramic Composite

↓ Joining

Ceramic Composite  
Channeled Ceramic Composite

Fabricate pairs of plate-shaped preforms, with one of the plates containing patterned milli-channels, via uniaxial pressing

Generate net-shape, net-size toughened ceramic composite plates via reaction process

Join pairs of ceramic composite plates\* and join plates to headers and tubing

\*Note: the reaction and joining processes for the ceramic composite plates may be conducted in the same step.

# Net-Shape, Net-Size Ceramic Composites

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- ◆ Green body (“preform”) plates with desired channel patterns are first generated by low-cost forming (e.g., pressing with stamped channel patterns).
  - ◆ The preform is then converted into the final desired high-temperature ceramic composite material via a *shape-preserving* reaction process.
  - ◆ The dimensional changes before and after such reaction are well below 1%. => This is also a *size-preserving* process.
- => Such a low-cost pressing/stamping and net-shape/size reaction process avoids:
- i) the chemical etching step of metallic alloy PCHEXs and
  - ii) the shrinkage and distortions associated with conventional ceramic sintering of shaped green bodies.

# Workplan

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## ◆ Processing Thrust:

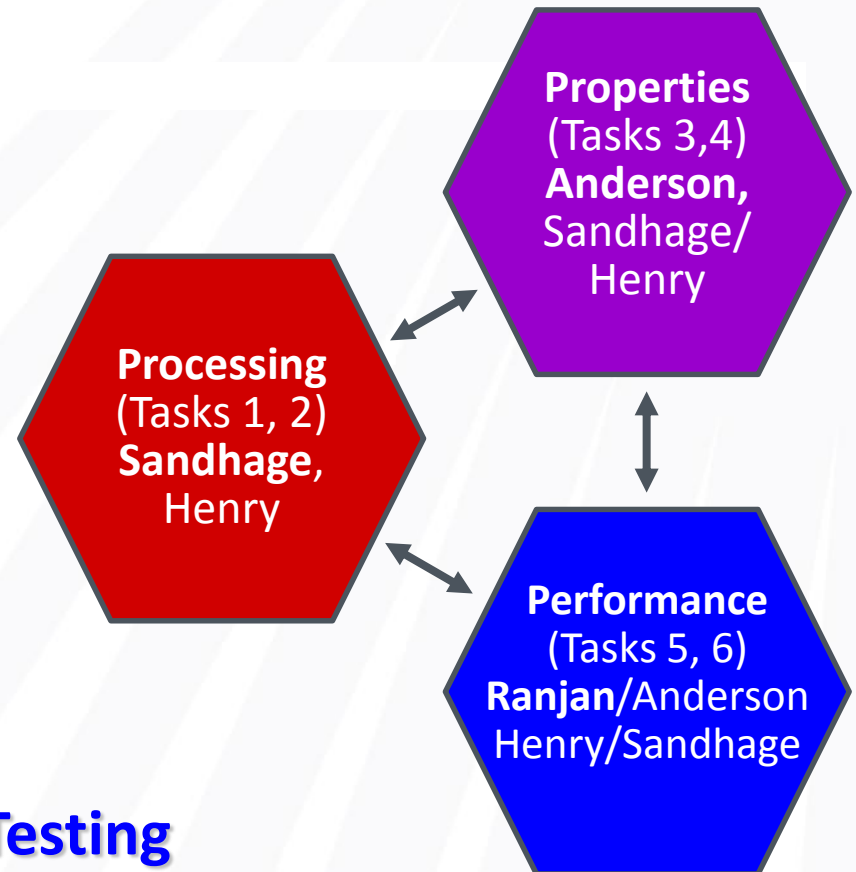
- Task 1: Manufacturing of Ceramic Composite HEXs
- Task 2: Component Joining

## ◆ Properties Thrust:

- Task 3: Corrosion Testing in Molten Salts, SC CO<sub>2</sub>
- Task 4: Thermal and Mechanical Properties

## ◆ Performance Thrust:

- Task 5: HEX Modeling and Testing
- Task 6: Techno-Economic Analyses





# Properties Thrust

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## ◆ Goal:

- To evaluate the chemical, thermal, and mechanical behavior of the ceramic composite materials

## ◆ Approaches:

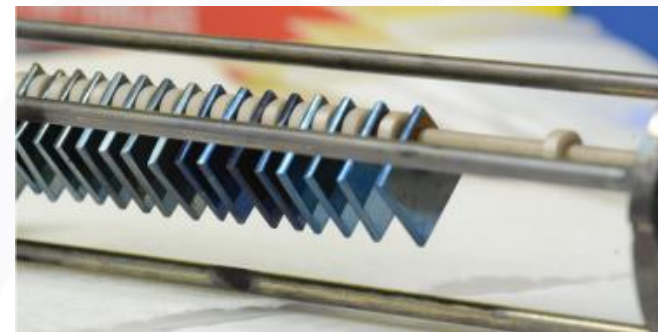
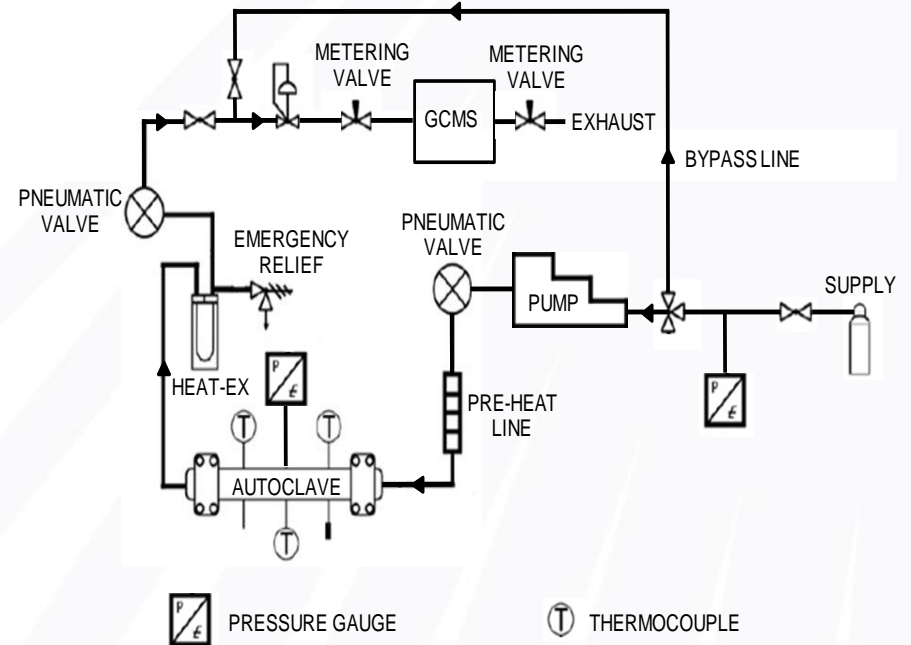
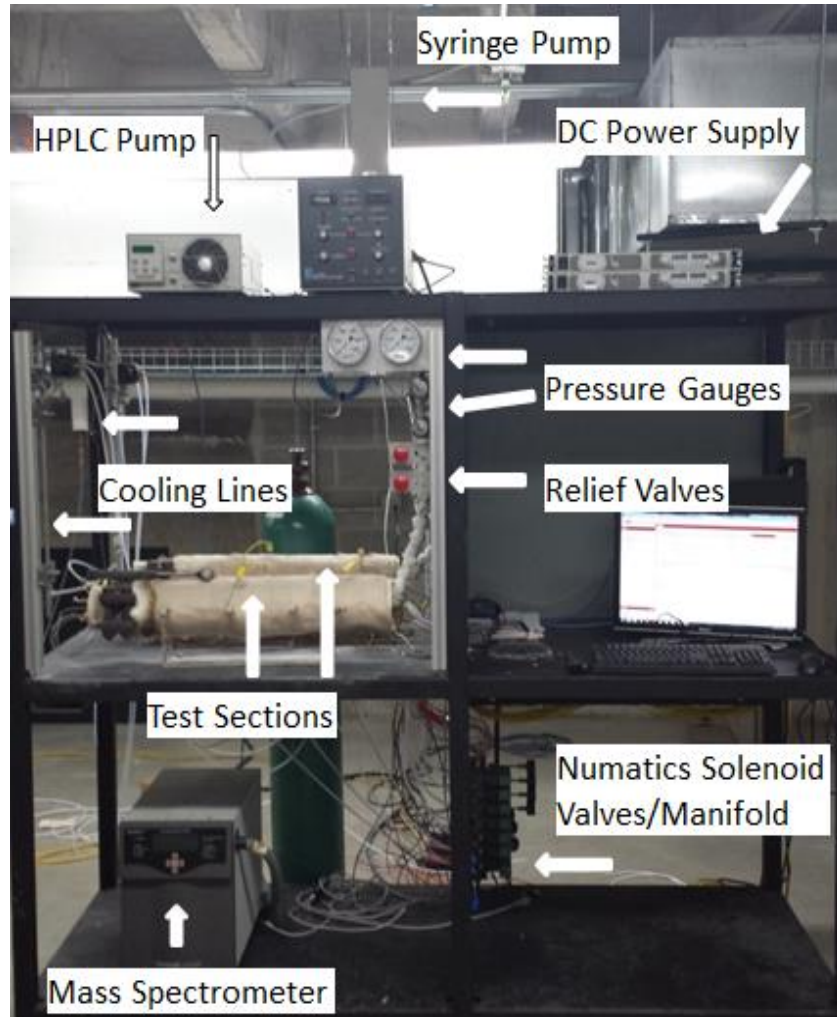
- Corrosion testing in SC-CO<sub>2</sub> at 750-800°C and 20 MPa
- Corrosion testing in molten chlorides (NaCl(l) and MgCl<sub>2</sub>-NaCl(l)) at  $\geq 800^\circ\text{C}$  and ambient pressure
- Laser flash tests to obtain thermal conductivity (as per ASTM standards E-1461/ASTM-E1269)
- Four point bend tests (as per ASTM standards C1161-13 and C1211-13)

Anderson, Sandhage,  
and Henry groups



# High-T, High-P, SC-CO<sub>2</sub> Corrosion Testing

## SC-CO<sub>2</sub> Autoclave Testing



# Performance Thrust

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## ◆ Goals:

- To develop a simulation framework to guide the design of ceramic composite-based HEXs with optimal geometries

## ◆ Approaches:

- A coupled Navier-Stokes and energy equation solver is being used to study thermohydraulic behavior inside the channels.

# Performance Thrust

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## ◆ Goals:

- To develop a simulation framework to guide the design of ceramic composite-based HEXs with optimal geometries
- To develop and utilize a HEX testing facility to evaluate the performance of ceramic composite-based HEXs

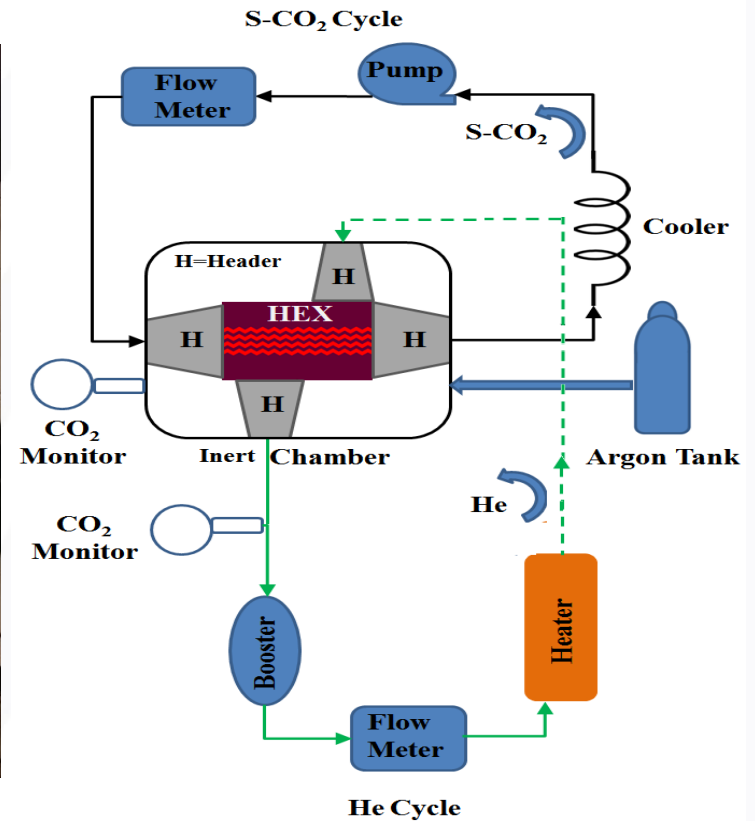
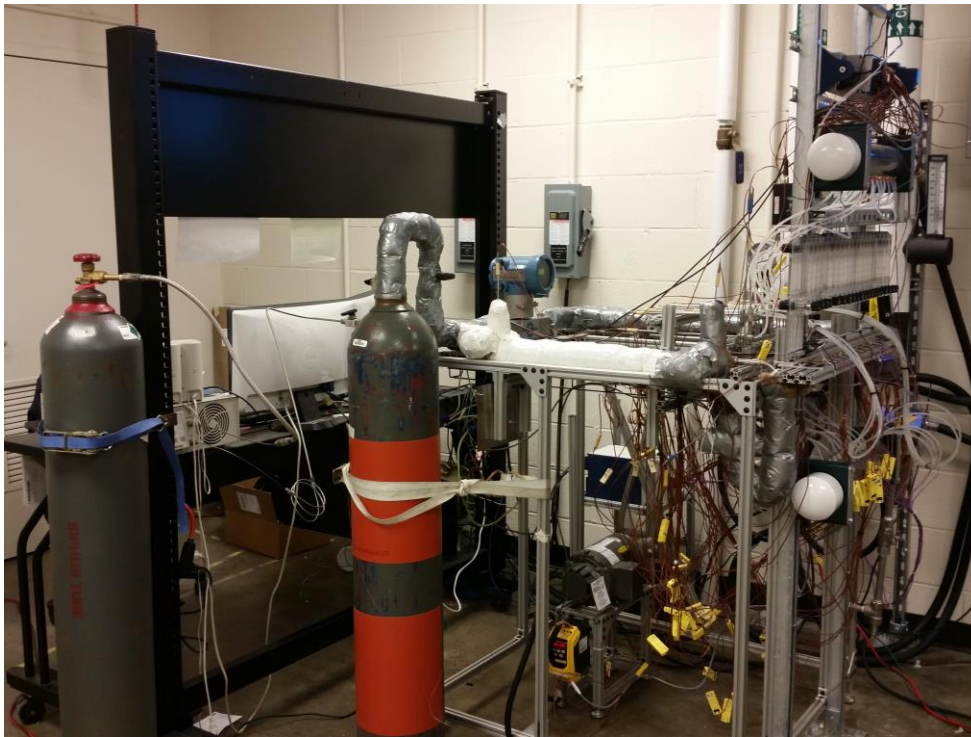
## ◆ Approaches:

- A coupled Navier-Stokes and energy equation solver is being used to study thermohydraulic behavior inside the channels.
- An existing test facility will be upgraded and instrumented for HEX testing (heat transfer, pressure drops) with flowing SC-CO<sub>2</sub>.



# Heat Exchanger Performance Testing

- ◆ A circulating SC-CO<sub>2</sub> loop capable of withstanding pressures of 20 MPa at temperatures up to 800°C



# Performance Thrust

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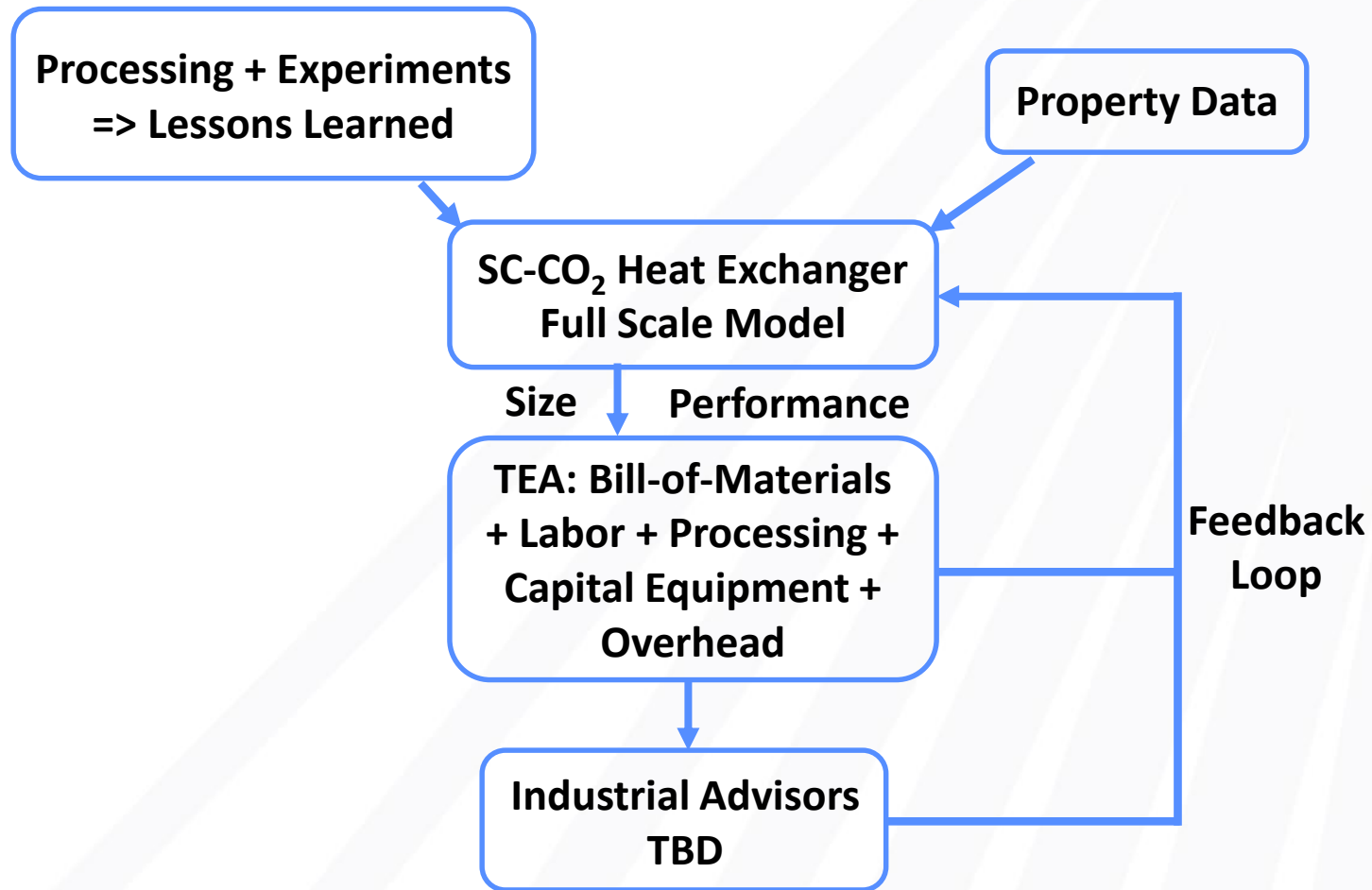
## ◆ Goals:

- To develop a simulation framework to guide the design of ceramic composite-based HEXs with optimal geometries
- To develop and utilize a HEX testing facility to evaluate the performance of ceramic composite-based HEXs
- To develop techno-economic models for the manufacturing of ceramic composite-based HEXs

## ◆ Approaches:

- A coupled Navier-Stokes and energy equation solver is being used to study thermohydraulic behavior inside the channels.
- An existing test facility will be upgraded and instrumented for HEX testing (heat transfer, pressure drops) with flowing SC-CO<sub>2</sub>.
- A T2M Advisor is being engaged to help develop detailed techno-economic models to help guide manufacturing scaleup.

# Detailed Techno-Economic Analyses



**Henry and Sandhage groups**



# Summary

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- ◆ **High-melting, thermally-conductive, stiff, toughened ceramic composite materials are being developed for use in high-temperature HEXs for CSP.**
- ◆ **A pressing/net-shape, net-size reaction/joining process is being evaluated for the scaled-up manufacturing of such ceramic composite-based HEXs.**
- ◆ **The thermal, mechanical, and chemical behavior of the ceramic composites are being evaluated for use as HEXs exposed to molten chlorides at  $\geq 800^{\circ}\text{C}$  and to SC-CO<sub>2</sub> at 750-800°C, 20 MPa.**
- ◆ **A simulation framework is being developed to guide the design of the HEXs for optimal heat transfer behavior.**
- ◆ **A detailed techno-economic model is being developed to determine the scaled-up manufacturing cost of the ceramic composite-based HEXs.**

**Questions?**  
**Suggestions?**